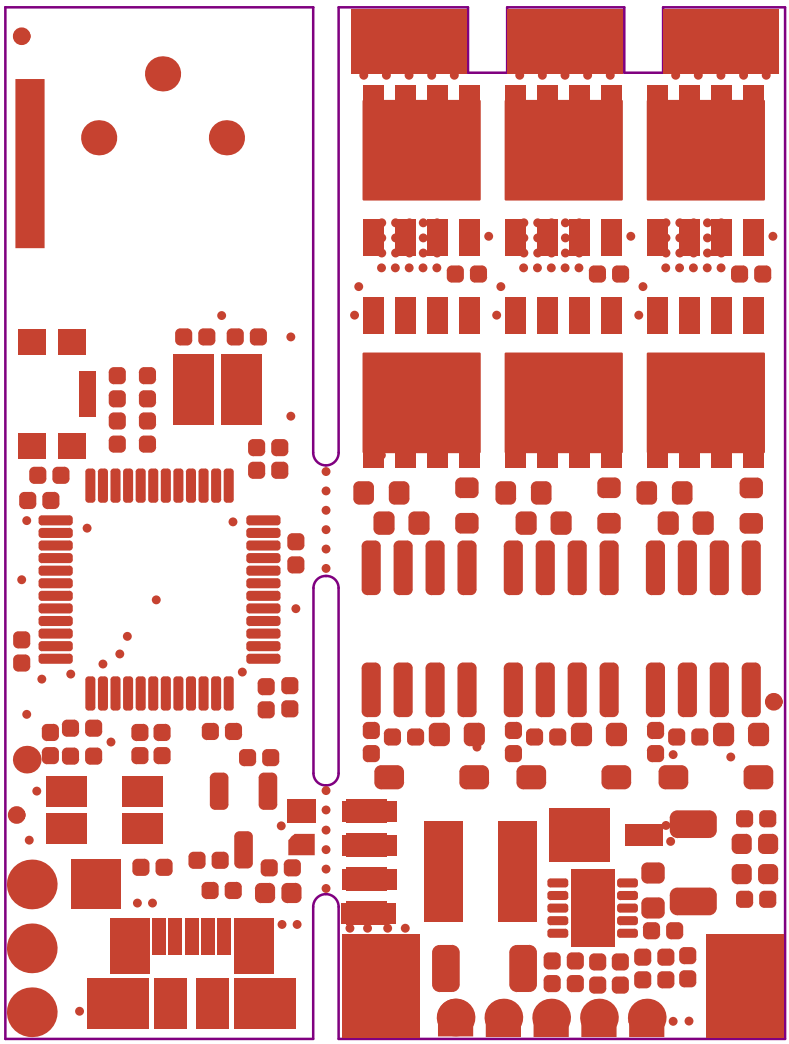


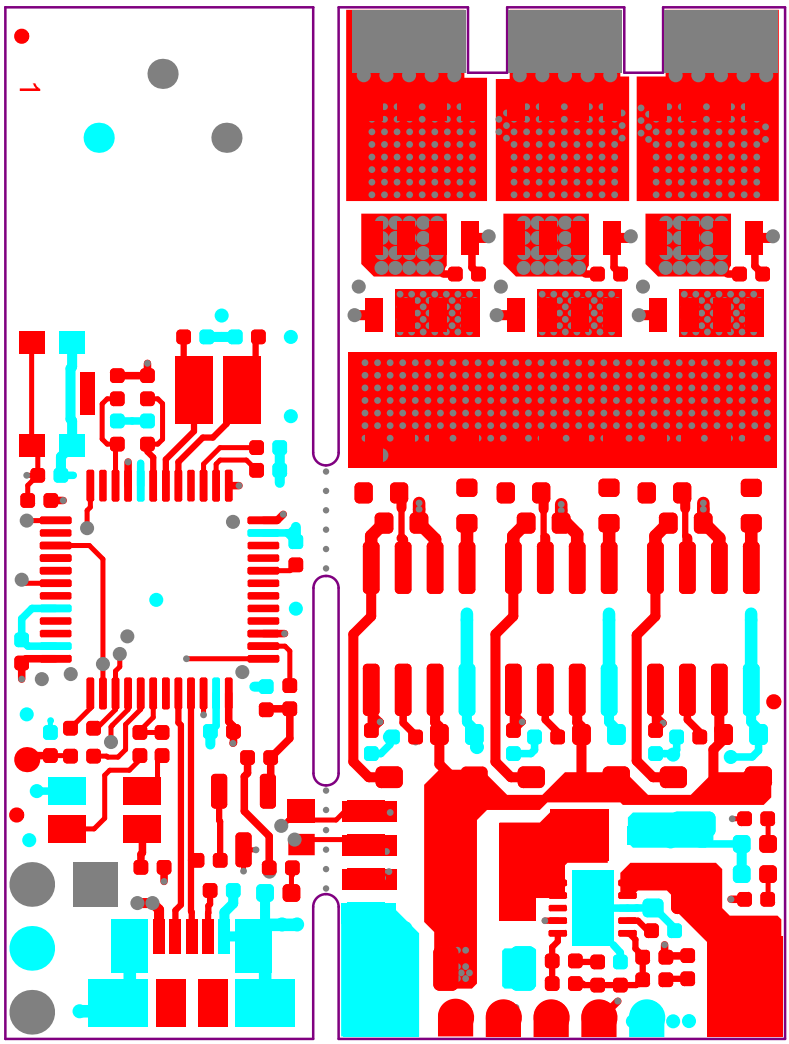
Top Overlay

.GTO



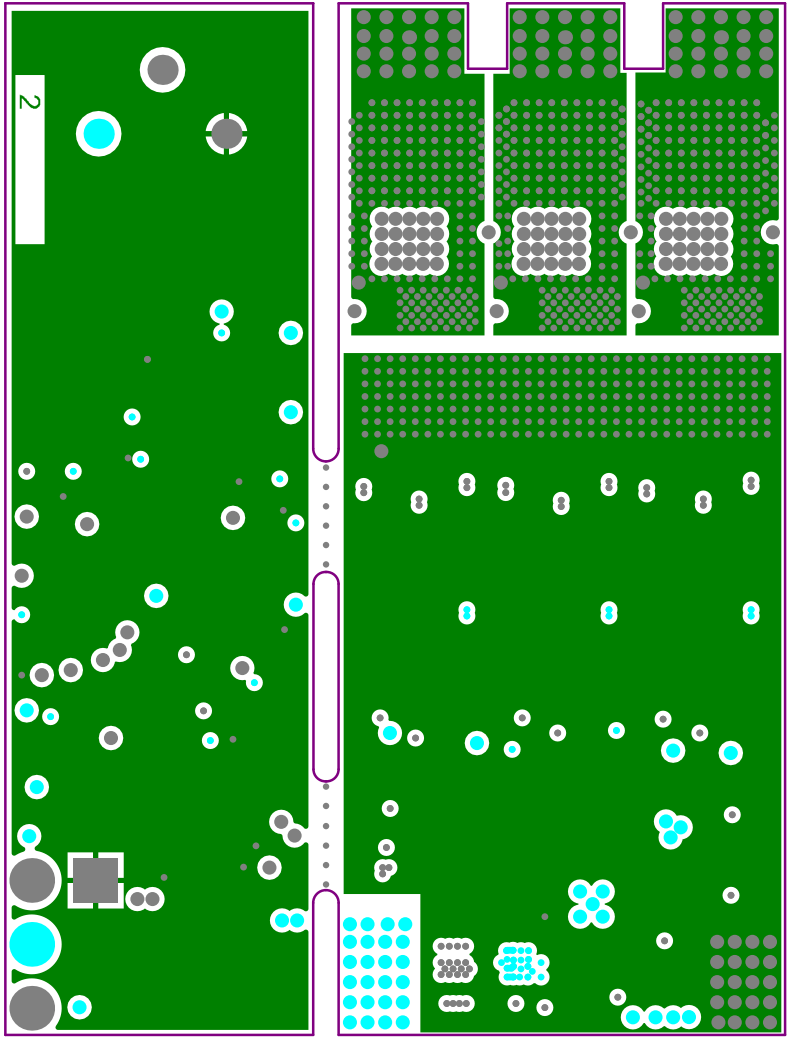
Top Solder

.GTS



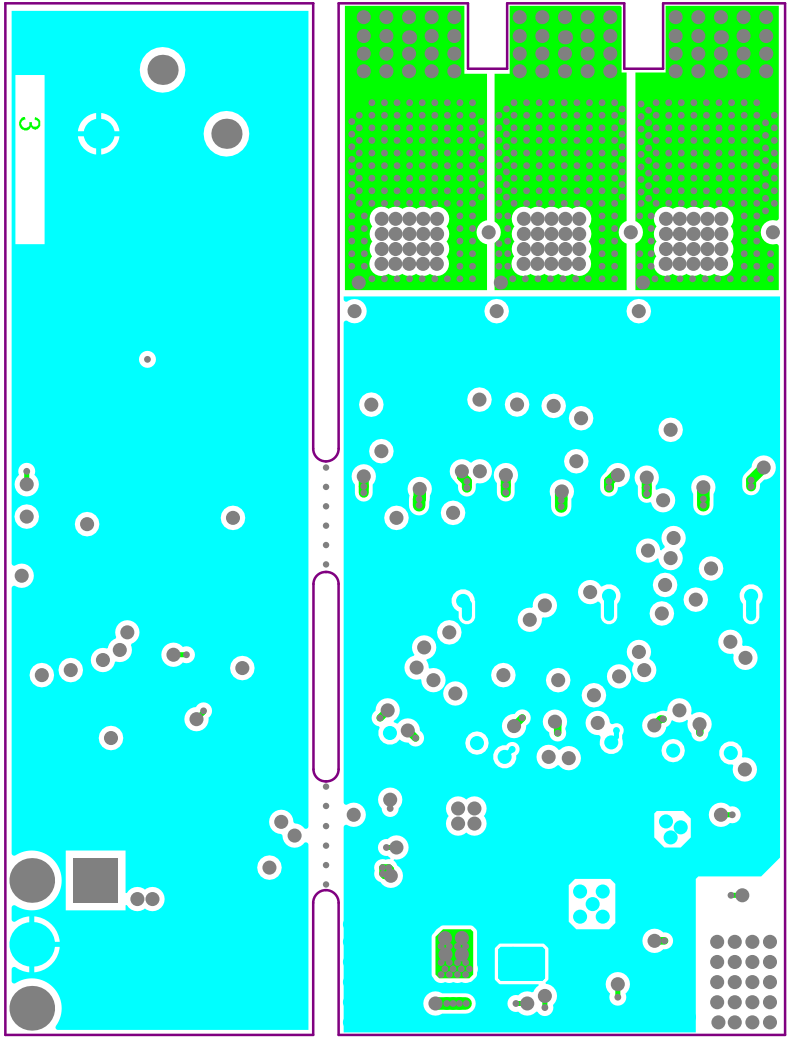
Top Layer

.GTL



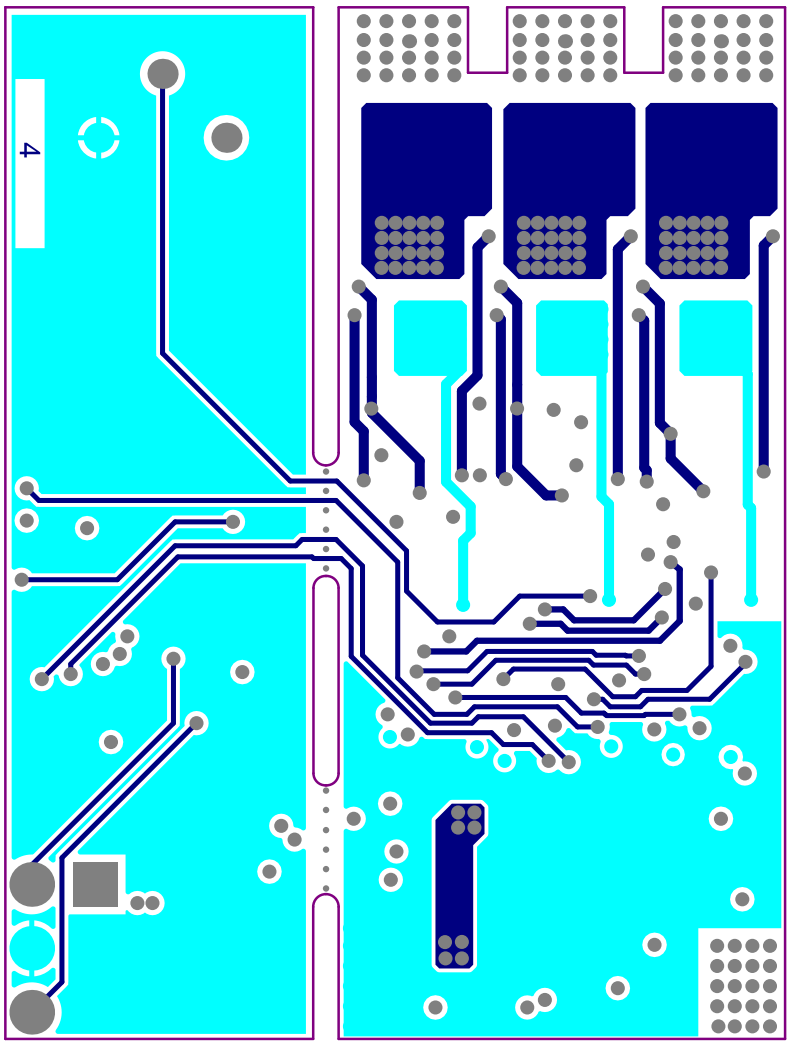
Signal Layer 1

.G1



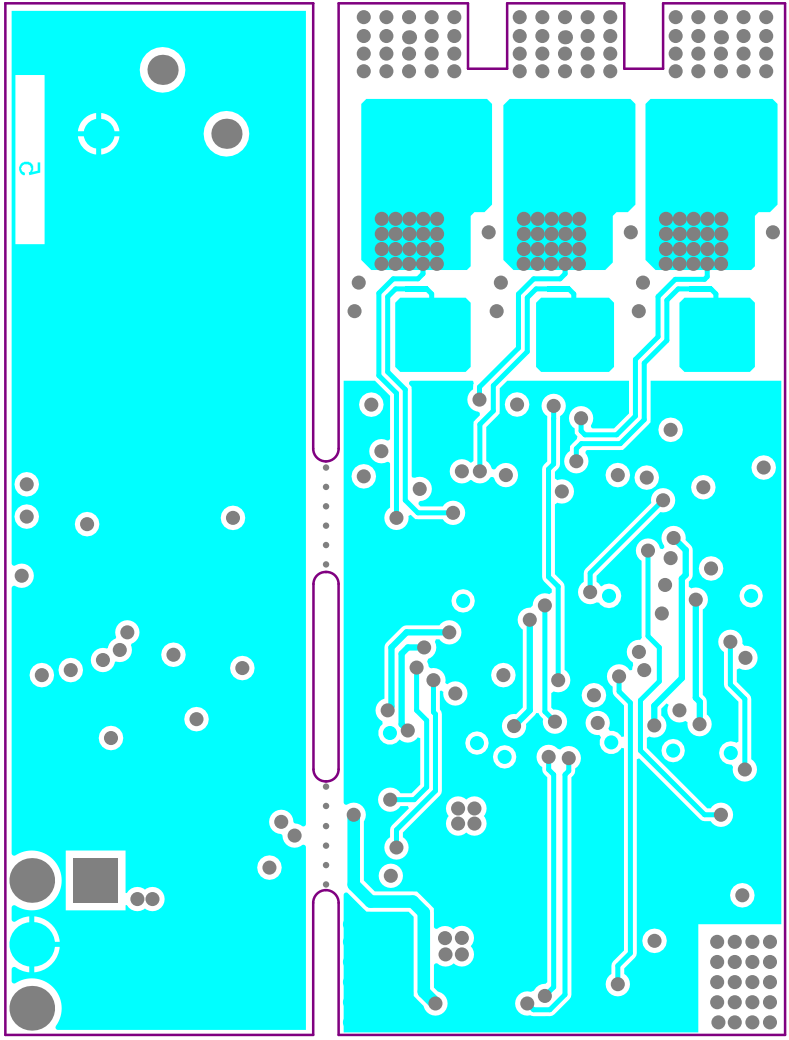
Signal Layer 2

.G2



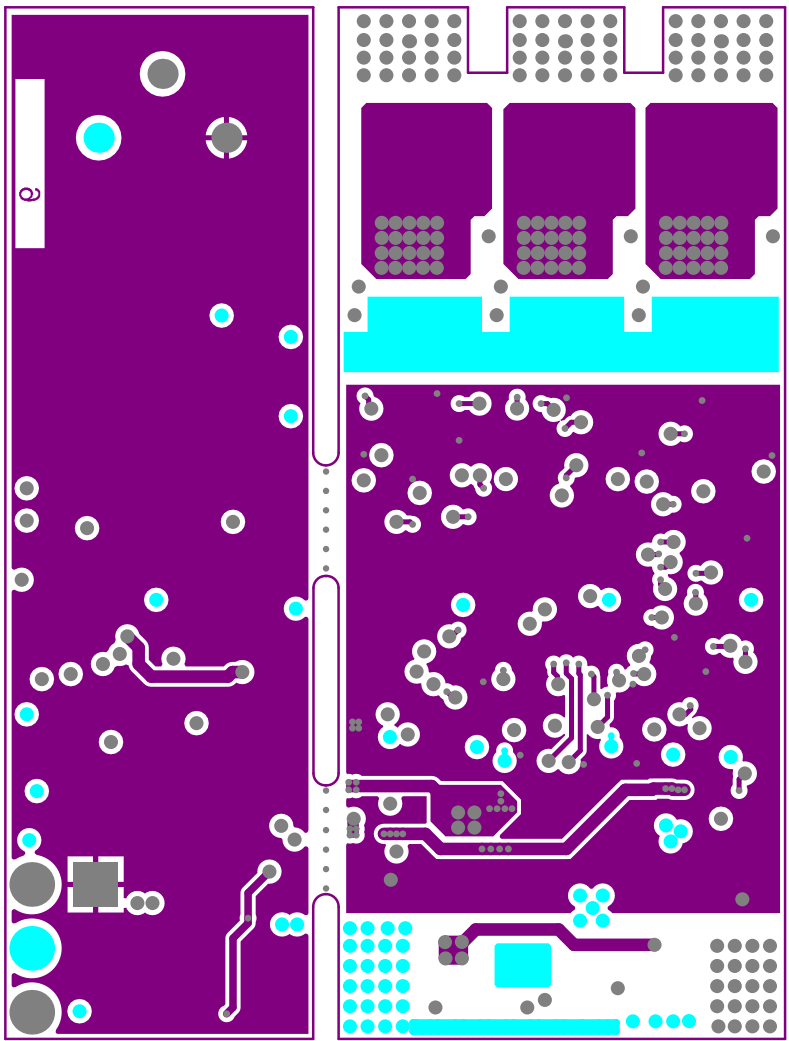
Signal Layer 3

.G3



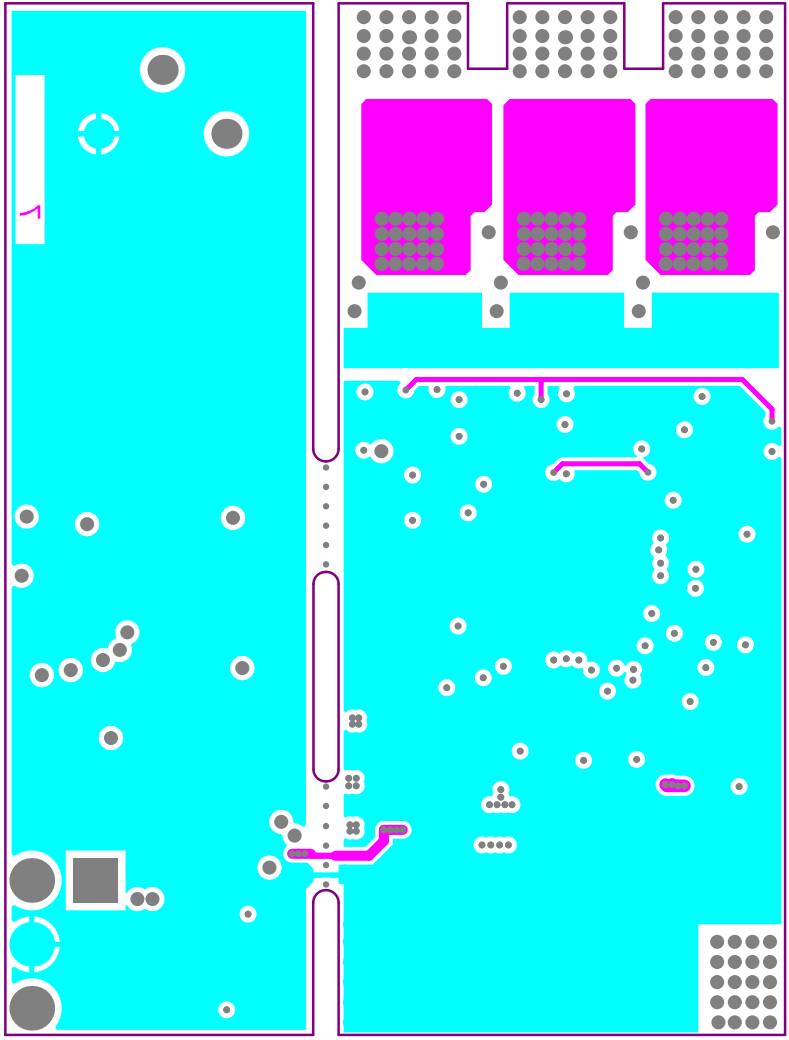
Signal Layer 4

.G4



Signal Layer 5

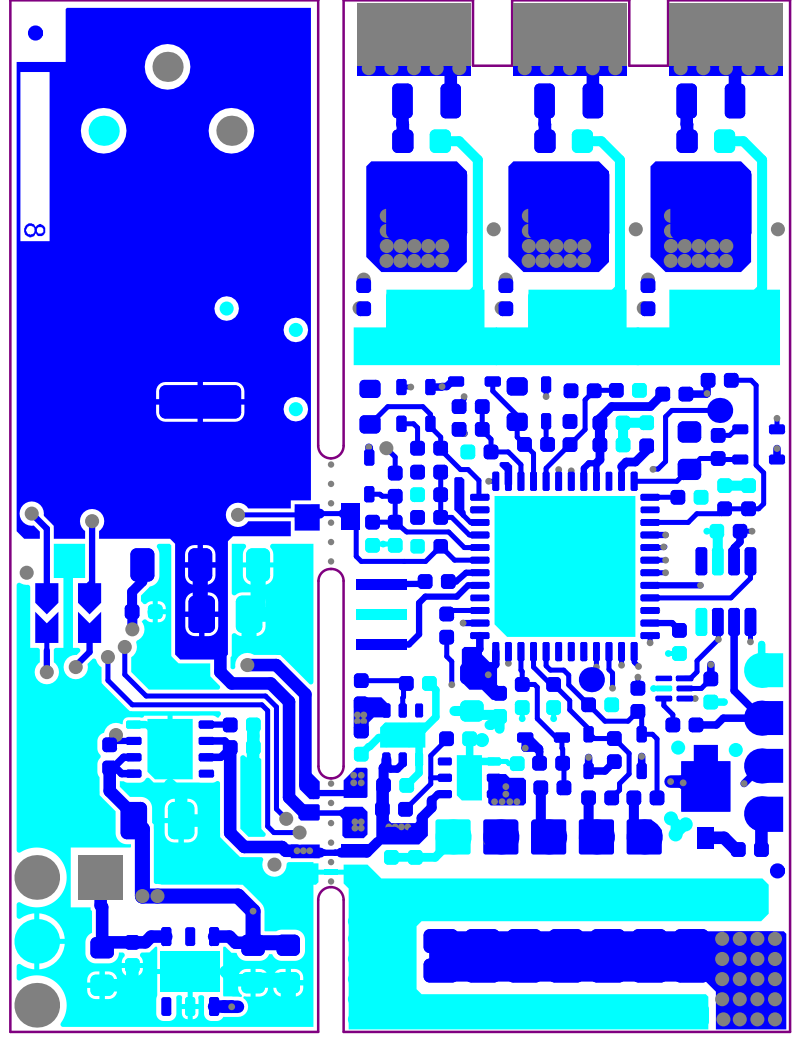
.G5



Signal Layer 6

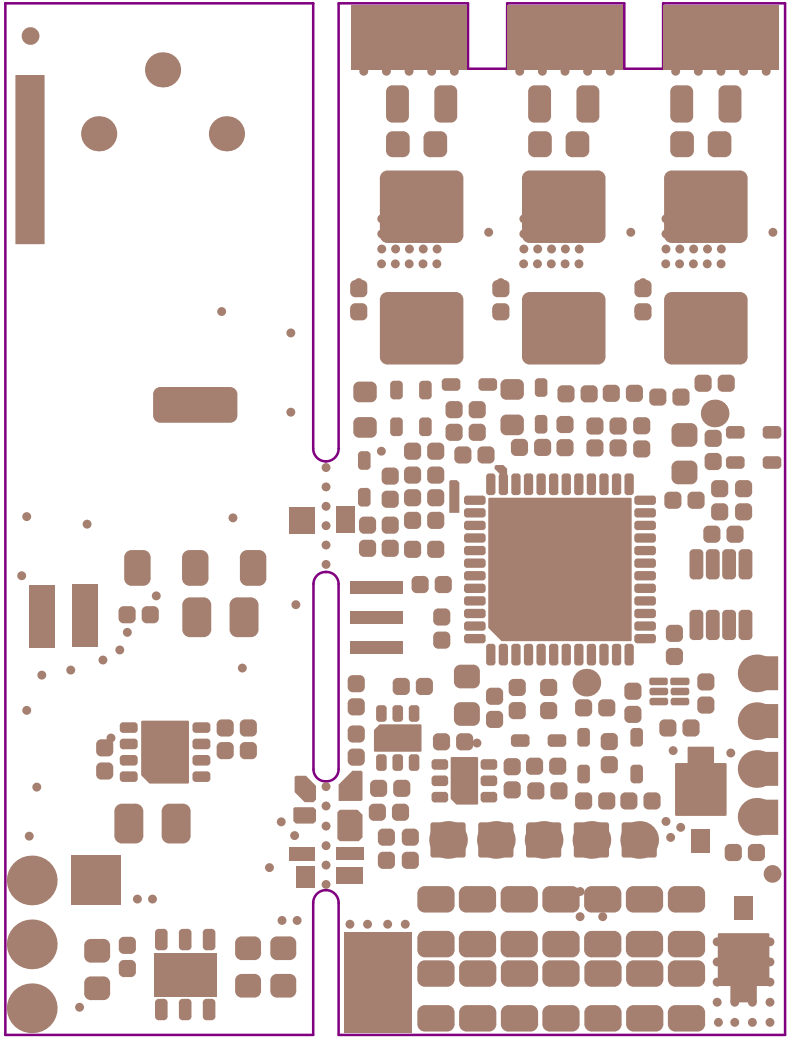
.G6

Bottom Layer



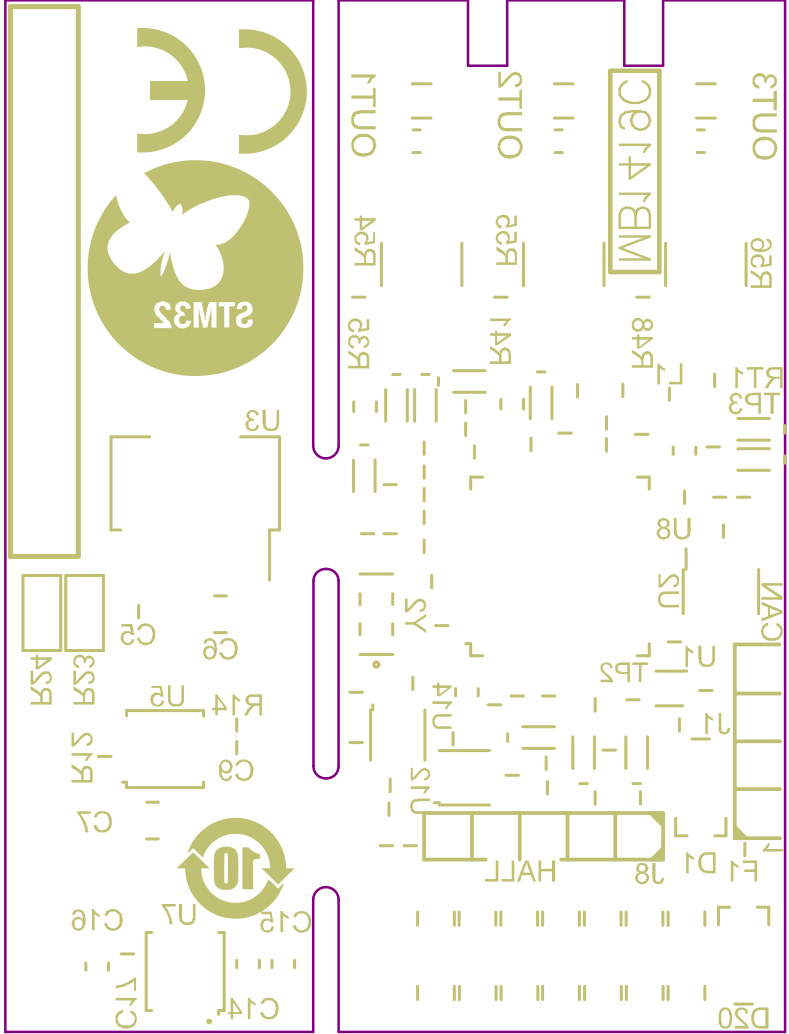
.GBL

Bottom Solder



.GB2

Bottom Overlay



.GBO

MINIMUM PARAMETERS

DEFAULT

TRACKS : 0.200mm

GAPS : 0.150mm

DRILL SIZE : 0.100mm

PCB : TYPE 4

ASPECT-RATIO, AXE Z :

6:1 to 8:1

LEVEL "B"

PCB SPECIFICATIONS :

A. MATERIAL :

FR-4

☐TG-170

☒TG-150

☐TG-140

B. MATERIAL FAMILY :

N/A

C. SOLDERMASK COLOR :

☐GREEN

☒BLUE

☐RED

☐BLACK

D. SILKSCREEN COLOR :

☒WHITE

☐YELLOW

☐BLACK

☐Blue ink PANTONE 2955

E. SURFACE FINISH :

☒ENIG

☐IMMERSION SILVER

☐IMMERSION TIN

☐HASL

☐HASL (PB-FREE)

☐GOLDEN FINGER

F. IMPEDANCE CONTROL :

☒NO

☐YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)

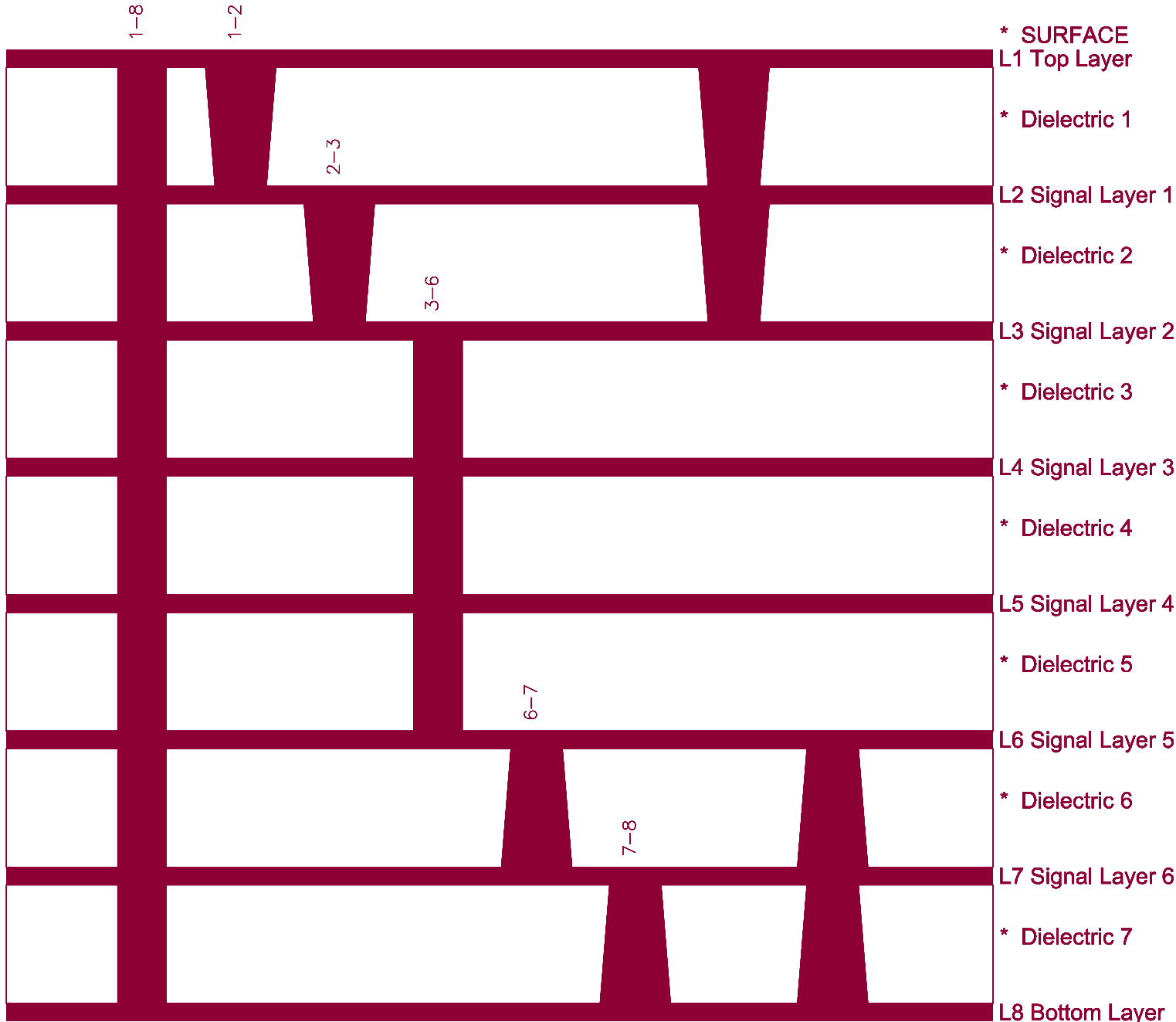
G. THROUGH VIA :

PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.

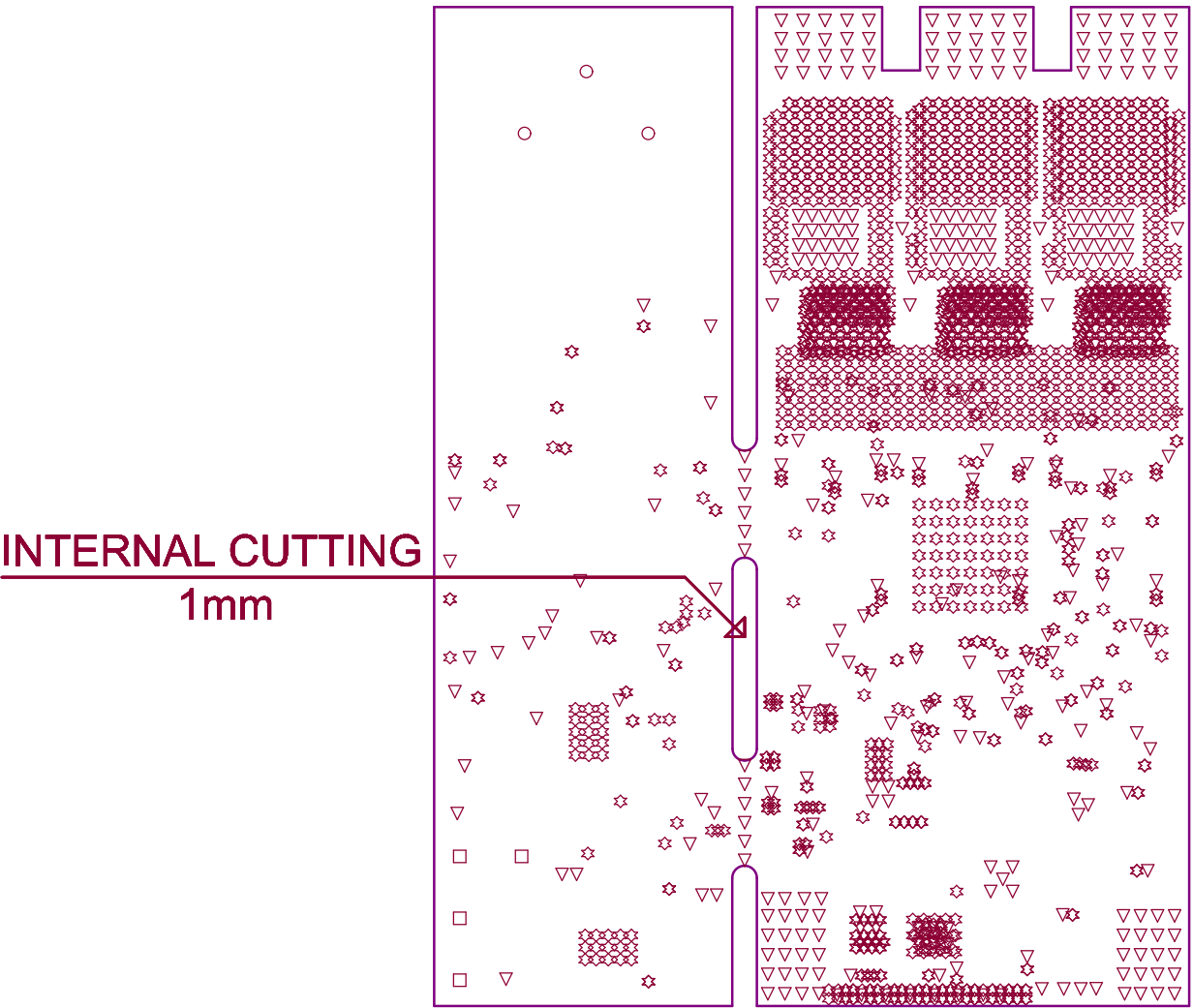
PLUG MATERIAL : ☒SOLDERMASK ☐NON-CONDUCTIVE EPOXY.

H. STACK-UP :

SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.



DESIGN CROSS SECTION CHART
TOTAL THICKNESS 1.55633mm



Drill Drawing

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad
	497	0,100mm (3,94mil)	PTH	Round	Signal Layer 1 - Signal Layer 2	Via
	497 Total					

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad
	503	0,100mm (3,94mil)	PTH	Round	Signal Layer 6 - Bottom Layer	Via
	503 Total					

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad
	309	0,100mm (3,94mil)	PTH	Round	Signal Layer 5 - Signal Layer 6	Via
	309 Total					

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad
	715	0,100mm (3,94mil)	PTH	Round	Top Layer - Signal Layer 1	Via
	715 Total					

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad
	155	0,254mm (10,00mil)	PTH	Round	Signal Layer 2 - Signal Layer 5	Via
	155 Total					

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad
	229	0,254mm (10,00mil)	PTH	Round	Top Layer - Bottom Layer	(Mixed)
	3	0,800mm (31,50mil)	PTH	Round	Top Layer - Bottom Layer	Pad
	4	0,991mm (39,00mil)	PTH	Round	Top Layer - Bottom Layer	Pad
	236 Total					

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0,010mm	3,5	
1	Top Layer	Copper	0,035mm		
	Dielectric 1		0,074mm	4,5	
2	Signal Layer 1	Copper	0,035mm		
	Dielectric 2		0,074mm	4,5	
3	Signal Layer 2	Copper	0,035mm		
	Dielectric 3		0,180mm	4,5	
4	Signal Layer 3	Copper	0,035mm		
	Dielectric 4		0,600mm	4,5	
5	Signal Layer 4	Copper	0,035mm		
	Dielectric 5		0,180mm	4,5	
6	Signal Layer 5	Copper	0,035mm		
	Dielectric 6		0,074mm	4,5	
7	Signal Layer 6	Copper	0,035mm		
	Dielectric 7		0,074mm	4,5	
8	Bottom Layer	Copper	0,035mm		
	Bottom Solder	Solder Resist	0,010mm	3,5	
	Bottom Overlay				

.DRL